



Material Content Data Sheet



Sales Product Name		TLS208D1EJ V33		Issued		27. September 2017		
MA#		MA001331470						
Package		PG-DSO-8-27		Weight*		84.01 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.453	1.73	1.73	17298	17298
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		433	
	non noble metal	iron	7439-89-6	0.728	0.87		8662	
wire	non noble metal	copper	7440-50-8	29.548	35.17	36.09	351712	360915
	noble metal	gold	7440-57-5	0.253	0.30	0.30	3013	3013
	encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1190
plastics		epoxy resin	-	4.598	5.47		54734	
	inorganic material	silicondioxide	60676-86-0	45.283	53.91	59.50	539013	594937
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8274	8274
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8624	8624
glue	plastics	epoxy resin	-	0.146	0.17		1735	
	noble metal	silver	7440-22-4	0.437	0.52	0.69	5204	6939
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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